

ALD precursors	Note
TMA	For Al ₂ O ₃ films
TiCl ₄	For TiO ₂ films
Electron beam evaporator pellets	Note
Al Cr Cu Ni Ti	For Lesker EBE1 and EBE2 tools
Etchants	Note
Al etchant	https://www.alfa.com/en/catalog/044581/
Buffered oxide etchant 7:1 (BoE)	
Cr etchant	https://www.alfa.com/en/catalog/044582/
Cu etchant	https://www.alfa.com/en/catalog/044583/
Liquid chemicals	Note
Acetone Hydrochloric acid (HCl) Hydrofluoric acid 49% (HF) Hydrogen peroxide 30% Isopropyl alcohol (IPA) Methanol Sulfuric acid (H ₂ SO ₄)	
Photoresists	Note
HMDS adhesion promoter	
Shipley 1818	For Suss and EVG 610 mask aligners
AZ5214	For Suss and EVG 610 mask aligners
950 PMMA A4	For electron beam lithography
494 PMMA A4	For electron beam lithography
PGMEA	
Nanoscribe resins	Note
IP-Visio Photoresist IP-Q Photoresist IP-Dip Photoresist IP-L Photoresist IP-S Photoresist	
Lithography developers and strippers	Note
TMAH 25% in water AZ 400T stripper AZ developer 1:1 AZ 300 MIF developer AZ 726 MIF developer MIBK/IPA developer MIF-319 developer	
Sputter Targets	Note
Au	For Cressington sputter coater
Al Cr Cu Ni Ti	For Lesker PVD75 DC tool
SiO ₂	For Lesker PVD75 RF tool
Al Al ₂ O ₃ Cu Hf Ir NbO ₂ Nb ₂ O ₅ Pt Si SiO ₂ Ta Ti TiN TiO ₂ Ru V ₂ O ₅ VO ₂ W	For Clustex